

WEST Search History

DATE: Monday, March 06, 2006

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<i>DB=PGPB,USPT,USOC,EPAB,JPAB,DWPI,TDBD; PLUR=YES; OP=ADJ</i>			
<input type="checkbox"/>	L2	6711775.pn.	3
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L1: Entry 2 of 2

File: DWPI

Sep 10, 2002

DERWENT-ACC-NO: 2000-387283

DERWENT-WEEK: 200274

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TITLE: Substrate cleaning involves simultaneously performing the removal of the contamination and etching process

INVENTOR: MIKHAYLICH, K ; SVIRCHEVSKI, J ; ZHANG, J

PATENT-ASSIGNEE:

ASSIGNEE	CODE
ONTRAK SYSTEMS INC	ONTRN
LAM RES CORP	LAMRN

PRIORITY-DATA: 1998US-0183568 (October 30, 1998), 2000US-0611235 (July 6, 2000)

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PATENT-FAMILY:

PUB-NO	PUB-DATE	LANGUAGE	PAGES	MAIN-IPC
JP 2002529910 W	September 10, 2002		032	H01L021/304
WO 200026944 A1	May 11, 2000	E	028	H01L021/00
US 6093254 A	July 25, 2000		000	B08B001/00
AU 9957992 A	May 22, 2000		000	H01L021/00
US 6170110 B1	January 9, 2001		000	B08B001/04
TW 410178 A	November 1, 2000		000	B08B011/00
EP 1125315 A1	August 22, 2001	E	000	H01L021/00
KR 2001087380 A	September 15, 2001		000	H01L021/306

DESIGNATED-STATES: AE AL AM AT AU AZ BA BB BG BR BY CA CH CN CR CU CZ DE DK DM EE ES FI GB GD GE GH GM HR HU ID IL IN IS JP KE KG KP KR KZ LC LK LR LS LT LU LV MD MG MK MN MW MX NO NZ PL PT RO RU SD SE SG SI SK SL TJ TM TR TT UA UG UZ VN YU ZA ZW AT BE CH CY DE DK EA ES FI FR GB GH GM GR IE IT KE LS LU MC MW NL OA PT SD SE SL SZ UG ZW AT BE CH CY DE DK ES FI FR GB GR IE IT LI LU MC NL PT SE

APPLICATION-DATA:

PUB-NO	APPL-DATE	APPL-NO	DESCRIPTOR
JP2002529910W	August 31, 1999	1999WO-US20044	
JP2002529910W	August 31, 1999	2000JP-0580234	

JP2002529910W		WO 200026944	Based on
WO 200026944A1	August 31, 1999	1999WO-US20044	
US 6093254A	October 30, 1998	1998US-0183568	
AU 9957992A	August 31, 1999	1999AU-0057992	
AU 9957992A		WO 200026944	Based on
US 6170110B1	October 30, 1998	1998US-0183568	Div ex
US 6170110B1	July 6, 2000	2000US-0611235	
US 6170110B1		US 6093254	Div ex
TW 410178A	October 15, 1999	1999TW-0117875	
EP 1125315A1	August 31, 1999	1999EP-0945388	
EP 1125315A1	August 31, 1999	1999WO-US20044	
EP 1125315A1		WO 200026944	Based on
KR2001087380A	April 26, 2001	2001KR-0705237	

INT-CL (IPC): B08 B 1/00; B08 B 1/04; B08 B 3/00; B08 B 3/08; B08 B 11/00;
C23 F 1/08; C23 G 1/00; C23 G 1/02; H01 L 21/00; H01 L 21/304; H01 L 21/306

ABSTRACTED-PUB-NO: US 6093254A

BASIC-ABSTRACT:

NOVELTY - A substrate is cleaned by placing it in a brush station, delivering a chemical solution to the station at a desired cleaning level, scrubbing the substrate and transporting the substrate into a second brush station, delivering used solution to the second station, stopping delivery of solutions, delivering water to the station, scrubbing the substrate with water.

DETAILED DESCRIPTION - AN INDEPENDENT CLAIM is also included for an apparatus for a brush assembly comprising a brush having a core, a rotation device, and a solution delivery system. The system has a mixing manifold that delivers a solution to the space in the core, and two delivery tubes coupled to pressure regulators and flow meters. The tube delivers the solutions at pressures and a flow rate to the mixing manifold.

USE - For cleaning a substrate.

ADVANTAGE - The invention increases the throughput of the system without using large amounts of chemicals and helps maintain control of the pH profile of a substrate during scrubbing. It enables the user to change the concentration of the chemical solution easily without having to premix the solutions.

DESCRIPTION OF DRAWING(S) - The drawing shows chemical profile of brushes and substrate surface in first and second brush stations.

ABSTRACTED-PUB-NO:

US 6170110B

EQUIVALENT-ABSTRACTS:

NOVELTY - A substrate is cleaned by placing it in a brush station, delivering a chemical solution to the station at a desired cleaning level, scrubbing the substrate and transporting the substrate into a second brush station, delivering used solution to the second station, stopping delivery of solutions, delivering water to the station, scrubbing the substrate with water.

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WO 200026944A

CHOSEN-DRAWING: Dwg. 6/6

TITLE-TERMS: SUBSTRATE CLEAN SIMULTANEOUS PERFORMANCE REMOVE CONTAMINATE ETCH PROCESS

DERWENT-CLASS: A88 L03 P43 U11

CPI-CODES: A04-F08; A12-D03; A12-E; L04-C07C; L04-C09;

EPI-CODES: U11-C06A1B;

ENHANCED-POLYMER-INDEXING:

Polymer Index [1.1] 018 ; R00835 G0566 G0022 D01 D11 D10 D12 D51 D53 D58 D63 D84 F41 F89 ; H0000 Polymer Index [1.2] 018 ; ND01 ; Q9999 Q6815 ; Q9999 Q7498 Q7330

SECONDARY-ACC-NO:

CPI Secondary Accession Numbers: C2000-117491

Non-CPI Secondary Accession Numbers: N2000-289955

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